



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
OCT -8 2002
TECHNOLOGY CENTER 2800

In re application of

Manabu MIZUSAKI

Confirmation No. 7669

Serial No. 09/847,370

GROUP 2827

Filed May 3, 2001

Examiner James M. Mitchell

ELECTRODE STRUCTURE OF A
CARRIER SUBSTRATE OF
SEMICONDUCTOR DEVICE

AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of July 10, 2002,
please amend the above-identified application as follows:

IN THE CLAIMS:

Amend claim 1 as follows:

C' --1. (twice amended) An electrode structure of a
carrier substrate of a semiconductor device for solder-bonding
the semiconductor device to a main substrate, said electrode
structure comprising:

a carrier substrate having a recess in a central area
of a surface thereof;

a soldering land of the electrode structure arranged in
the recess, said soldering land having a circumferential wall
defining a hollow portion extending from said surface, said
circumferential wall being entirely within said recess; and